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U.S. UTILITY Patent Application

APPL NUM 10009822	FILING DATE 12/13/2001	CLASS 361	SUBCLASS 2835	GAU <i>KOELLER</i>	EXAMINER LA VILLA
**APPLICANTS: Osada Mitsuo; Hirayama Norio; Arikawa Tadashi; Amano Yoshinaro; Maesato Hidetoshi; Hayashi Hidefumi; Murai Hiroshi;					<i>12/13/2001</i>
**CONTINUING DATA VERIFIED: THIS APPLICATION IS A 371 OF PCT/JP01/03164 04/12/2001 <i>m</i>					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 17584/2000 01/26/2000 JAPAN 113006/2000 04/14/2000 <i>two m</i> JAPAN 372405/2000 12/07/2000 <i>m</i>					
PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>			
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiner's initials <i>m</i>		<input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input checked="" type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO Q67726	
TITLE : Material of heat-dissipating plate on which semiconductor is mounted, method for fabricating the same, and ceramic package produced by using the same					
U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-94)					

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NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims <i>6</i>	Print Claim for O.G. <i>1</i>
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drawn <i>3</i>	Fig.s Drawn <i>7</i>
TERMINAL DISCLAIMER		Print Fig. <i>4</i>	
		Primary Examiner <i>Michael LaVilla</i>	
		PREPARED FOR ISSUE	
		Application Examiner <i></i>	
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